

ABSTRACT

The palladium remover of the present invention comprises (a) a nitrate, (b) a water-solubilizer for making palladium oxide water-soluble, and (c) water.

5 The palladium remover may further contain (d) a wetting agent and/or (e) a chelating agent. The palladium remover removes palladium remaining on the surface of an insulating substrate without corroding copper wires and without roughening the surface of the insulating substrate, thereby enhancing the insulation of the circuit patterns.



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